ON Semiconductor

Is Now

Onsemi

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MOSFET - Power, N-Channel, SUPERFET[®] III, FAST 650 V, 125 mΩ, 24 A

NTPF125N65S3H

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provides superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III FAST MOSFET series helps minimize various power systems and improve system efficiency.

Features

- 700 V @ $T_J = 150^{\circ}C$
- Typ. $R_{DS(on)} = 108 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q_g = 44 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 379 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

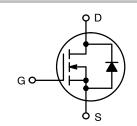
- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Industrial Power Supplies
- Lighting / Charger / Adapter



ON Semiconductor®

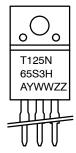
www.onsemi.com

V _{DSS}	V _{DSS} R _{DS(ON)} MAX	
650 V	125 m Ω @ 10 V	24 A





MARKING DIAGRAM



T125N65S3H = Specific Device Code

= Assembly Location = Year

А

Y

- WW = Work Week
- ZZ = Lot Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter	Value	Unit	
V _{DSS}	Drain to Source Voltage		650	V
V _{GSS}	Gate to Source Voltage	DC	±30	V
		AC (f > 1 Hz)	±30	V
Ι _D	Drain Current	Continuous (T _C = 25°C)	24*	А
		Continuous (T _C = 100°C)	15*	
I _{DM}	Drain Current	rain Current Pulsed (Note 1)		А
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		216	mJ
I _{AS}	Avalanche Current (Note 2)		4.7	А
E _{AR}	Repetitive Avalanche Energy (Note 1)		1.71	mJ
dv/dt	MOSFET dv/dt		120	V/ns
	Peak Diode Recovery dv/dt (Note 3)		20	
PD	Power Dissipation	(T _C = 25°C)	37	W
		Derate Above 25°C	0.30	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		–55 to +150	°C
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 s		260	°C

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, Unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. *Drain current limited by maximum junction temperature.

1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. $I_{AS} = 4.7 \text{ A}, R_G = 25 \Omega$, starting $T_J = 25^{\circ}\text{C}$. 3. $I_{SD} \le 12 \text{ A}, \text{ di/dt} \le 200 \text{ A/}\mu\text{s}, \text{ V}_{DD} \le 400 \text{ V}, \text{ starting } T_J = 25^{\circ}\text{C}$.

THERMAL CHARACTERISTICS

Symbol	Symbol Parameter		Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	3.37	°C/W
$R_{\theta JA}$	$R_{\theta JA}$ Thermal Resistance, Junction to Ambient, Max.		

PACKAGE MARKING AND ORDERING INFORMATION

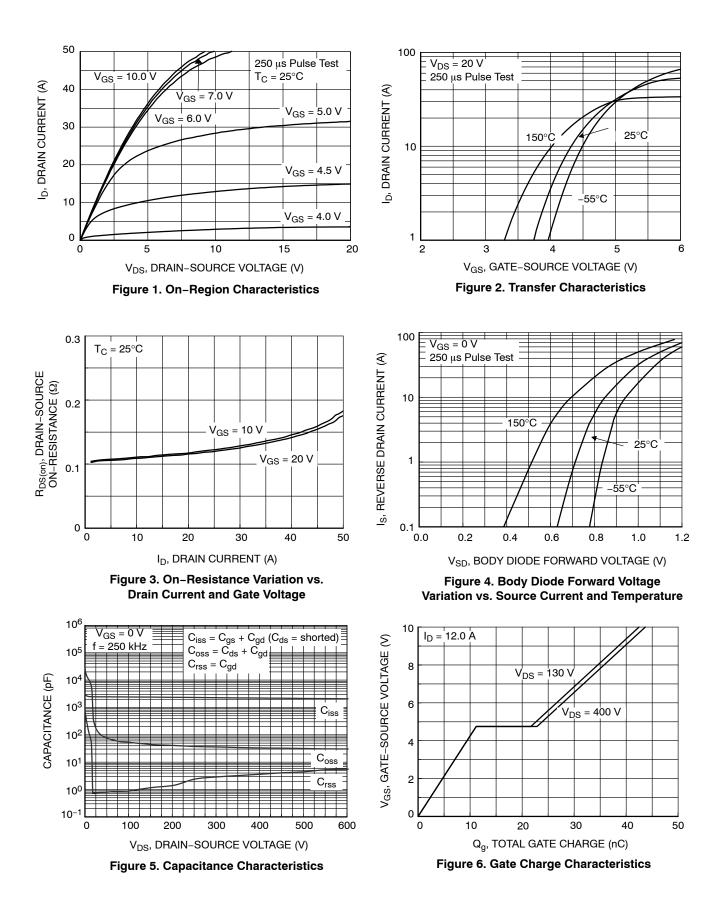
Part Number	Top Marking	Package	Shipping
NTPF125N65S3H	T125N65S3H	TO-220 FULLPAK	50 Units / Tube

FI FCTRICAL CHARACTERISTICS (Tc = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS					
BV _{DSS}	Drain to Source Breakdown Voltage	V_{GS} = 0 V, I_D = 1 mA, T_J = 25°C	650			V
		V_{GS} = 0 V, I _D = 1 mA, T _J = 150°C	700			V
$\Delta \text{BV}_{\text{DSS}}\!/\!\Delta\text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 10 mA, Referenced to 25°C		0.63		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 650 V, V_{GS} = 0 V			1	μΑ
		V_{DS} = 520 V, T_C = 125°C		1.3		
I _{GSS}	Gate to Body Leakage Current	V_{GS} = ±30 V, V_{DS} = 0 V			±100	nA
ON CHARACTE	RISTICS					-
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.1 \text{ mA}$	2.4		4.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V_{GS} = 10 V, I _D = 12 A		108	125	mΩ
9 _{FS}	Forward Transconductance	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 12 \text{ A}$		26		S
	RACTERISTICS					
C _{iss}	Input Capacitance	V_{DS} = 400 V, V_{GS} = 0 V, f = 250 kHz		2200		pF
Coss	Output Capacitance			34		pF
C _{oss(eff.)}	Effective Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V		379		pF
C _{oss(er.)}	Energy Related Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V		56		pF
Q _{g(tot)}	Total Gate Charge at 10 V			44		nC
Q _{gs}	Gate to Source Gate Charge	V _{DS} = 400 V, I _D = 12 A, V _{GS} = 10 V (Note 4)		11		nC
Q _{gd}	Gate to Drain "Miller" Charge			12		nC
ESR	Equivalent Series Resistance	f = 1 MHz		1.1		Ω
WITCHING CH	IARACTERISTICS					
t _{d(on)}	Turn-On Delay Time			22		ns
t _r	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 12 \text{ A},$		9.2		ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, R _g = 7.5 Ω (Note 4)		66		ns
t _f	Turn-Off Fall Time			2.3		ns
OURCE-DRAI	N DIODE CHARACTERISTICS			•		
۱ _S	Maximum Continuous Source to Drain Diode Forward Current				24	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current				67	Α
V _{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I_{SD} = 12 A			1.2	V
t _{rr}	Reverse Recovery Time	V _{DD} = 400 V, I _{SD} = 12 A,		314		ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$		4.5		μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially independent of operating temperature typical characteristics.

TYPICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)



TYPICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted) (continued)

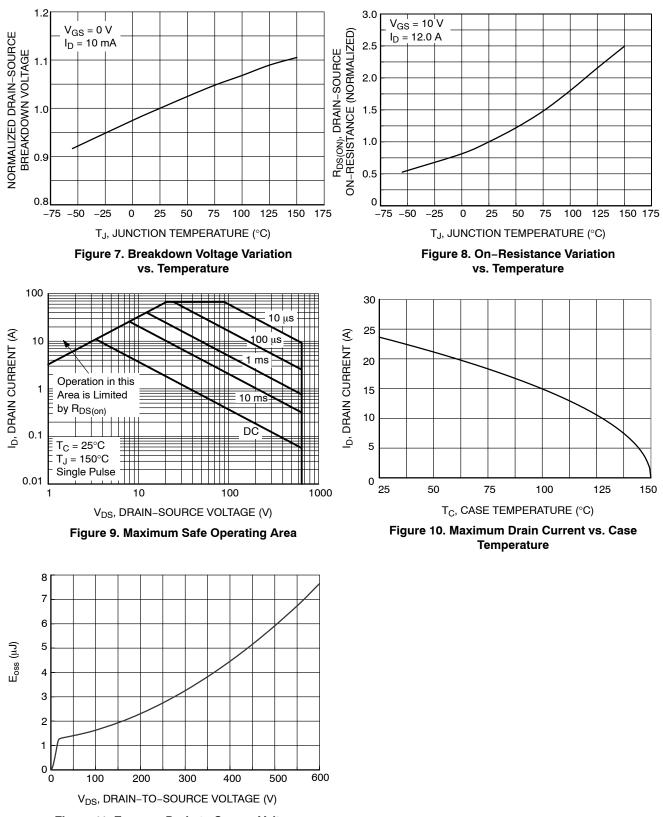


Figure 11. E_{OSS} vs. Drain to Source Voltage

TYPICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted) (continued)

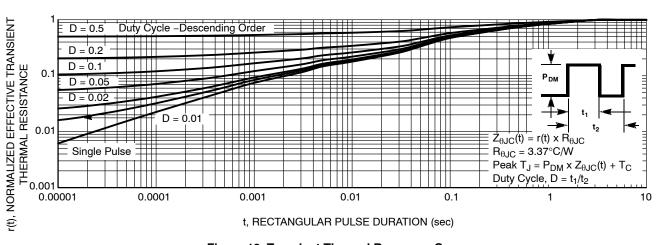
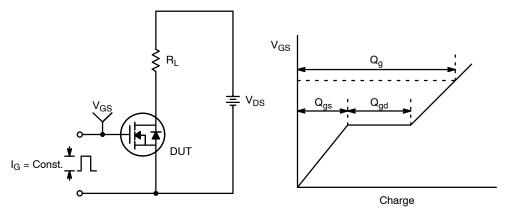


Figure 12. Transient Thermal Response Curve





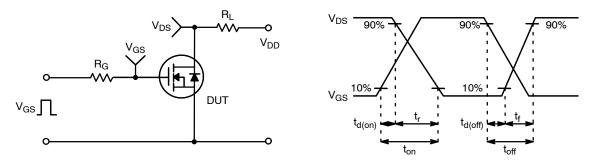


Figure 14. Resistive Switching Test Circuit & Waveforms

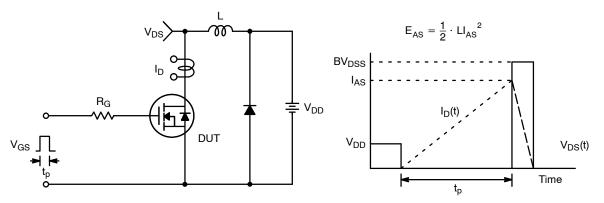


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

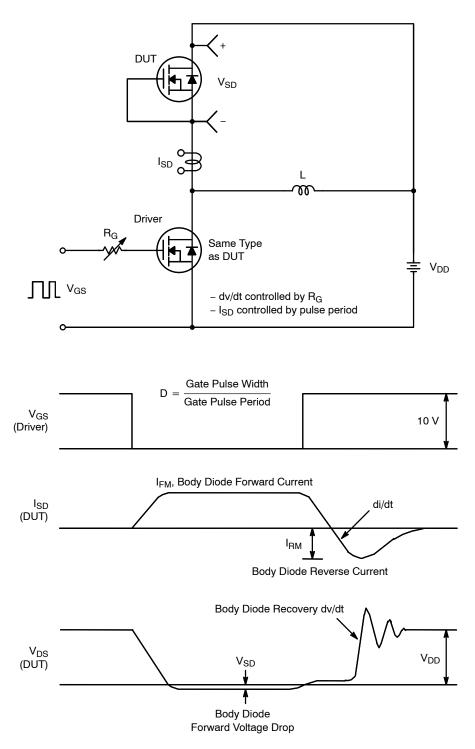
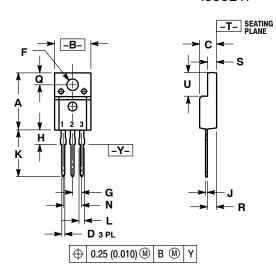


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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PACKAGE DIMENSIONS

TO-220 FULLPAK CASE 221D-03 ISSUE K



NOTES

1. DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982

CONTROLLING DIMENSION: INCH 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03. 3.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.617	0.635	15.67	16.12
В	0.392	0.419	9.96	10.63
С	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100 BSC		2.54 BSC	
Н	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
Κ	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
Ν	0.200 BSC		5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

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